

Listing of Claims

Claims 1-54 (Canceled)

55. (currently amended) A method for burn-in testing a semiconductor die having a pad comprising:

providing a ~~test~~ fixture ~~comprising an external lead~~ for establishing electrical contact between the die and a burn-in oven, the fixture comprising a plate for receiving the die, an external lead on the plate, a cover configured for attachment to the plate, and a film comprising a bump for electrically contacting the pad and a conductive trace in electrical communication with the bump and the external lead;

~~providing a plastic film comprising a bump for electrically contacting the pad, and a conductive trace in electrical communication with the bump and the external lead;~~

placing the die face up on the ~~test fixture plate~~ and the film on the die with the bump on the pad; and

~~placing~~ assembling the fixture by securing the cover to the plate with the film biased against the die and the bump in to electrical contact with the pad; and

placing the external lead in electrical contact with the burn-in oven.

56. (currently amended) The method of claim 55 wherein the providing step ~~test fixture~~ comprises providing the fixture with a plurality of external leads and the ~~plastic film comprises~~ with a plurality of bumps and a plurality of conductive traces in electrical communication with the bumps.

57. (currently amended) The method of claim 55 wherein the providing step comprises providing the fixture with a compressible member and the ~~placing the bump~~

assembling step is performed with a the compressible member ~~in the test fixture configured to biasing~~ the film against the die.

~~bump against the pad.~~

58. (currently amended) The method of claim 55 wherein the providing step comprises providing the fixture with a cavity on the plate for the die.

~~test fixture comprises a cover and a compressible member on the cover and the placing the bump step is performed using the compressible member and the cover.~~

59. (currently amended) The method of claim 55 wherein the providing step comprises providing the fixture with a clamp and the assembling step comprises securing the cover to the plate with the clamp.

~~placing the bump step is performed by bonding the bump to the pad.~~

60. (previously presented) The method of claim 55 wherein the pad comprises a bondpad.

61. (currently amended) A method for burn-in testing a semiconductor die having a plurality of pads comprising:

providing a ~~test fixture comprising a compressible member and a plurality of external leads~~ for establishing electrical contact between the die and a burn-in oven, the fixture comprising a plate having a plurality of external leads, a cover, a compressible member and a film comprising a plurality of bumps in electrical communication with the external leads;

~~providing a plastic film comprising a plurality of bumps for electrically contacting the pads, and a plurality of conductive traces in electrical communication with the bumps and the external leads;~~

placing the die face up on the ~~test fixture~~ plate
and the ~~plastic~~ film on the die with the bumps on the pads;

assembling the fixture by securing the cover and
the compressible member to the plate and biasing the film
against the die; and

~~biasing the bumps into electrical contact with~~
~~the pads using the compressible member; and~~

placing the external leads in electrical contact
with the burn-in oven.

62. (previously presented) The method of claim 61
wherein the pads comprise bond pads.

F1 cont.
63. (currently amended) The method of claim 61
wherein the ~~plastic~~ film comprises a plurality of ~~second~~
~~bumps in electrical communication with the~~ conductive
traces ~~and~~ configured to establish electrical communication
with between the bumps and the external leads.

64. (previously presented) The method of claim 61
wherein the external leads comprise pins in a dual in line
(DIP) configuration.

65. (previously presented) The method of claim 61
wherein the external leads comprise pins in a quad flat
pack (QFP) configuration.

66. (currently amended) The method of claim 61
wherein the compressible member comprises an elastomeric
strip.

~~test fixture comprises a plate for the die, a cover~~
~~attached to the compressible member and a clip for~~
~~attaching the cover to the plate.~~

67. (currently amended) A method for burn-in testing
a semiconductor die having a pad comprising:

providing a ~~test~~ fixture comprising a plate, a contact on the plate, and an external lead on the plate in electrical communication with the contact;

~~for establishing electrical contact between the die and a burn-in oven;~~

providing the fixture with a die contact member ~~for electrically connecting the pad to the external lead, the member~~ comprising a plastic film, a first bump on the plastic film for electrically contacting the pad, a conductive trace on the plastic film in electrical communication with the first bump, and a second bump on the plastic film in electrical communication with the conductive trace;

P1 cont.
placing assembling the fixture with the die on in the test fixture plate and the plastic film biased against the die with the first bump in contact with the pad and the second bump in contact with the contact; and

~~placing the first bump in electrical contact with the pad on the die;~~

~~placing the second bump in electrical contact with the contact on the plate; and~~

placing the external lead in electrical contact with the burn-in oven.

68. (currently amended) The method of claim 67 wherein the pad comprises a bondpad.

~~placing the first bump step comprises biasing the first bump against the pad.~~

69. (currently amended) The method of claim 67 wherein the providing the fixture step comprises providing the fixture with a compressible member configured to bias the plastic film against the die during the assembling step.

~~placing the first bump step comprises biasing the first bump against the pad using a compressible member on the plate.~~

70. (currently amended) The method of claim 67 wherein the plastic film comprises polyamide.
~~placing the first bump step comprises bonding the first bump to the pad.~~

71. (currently amended) The method of claim 67 wherein the ~~placing the first bump step comprises bonding~~ the second bump is bonded to the contact.

72. (currently amended) A method for burn-in testing a semiconductor die having a pad comprising:

providing a ~~test~~ fixture comprising a plate, an external lead on the plate, a cover and a compressible member configured for attachment to the plate, and a film comprising a bump for electrically contacting the pad and a conductive trace in electrical communication with the bump and the external lead;

assembling the fixture by placing the die on the plate, the film on the die, the compressible member on the film and then attaching the cover to the plate with the compressible member biasing the film against the die with the bump in electrical contact with the pad; and
~~for establishing electrical contact between the die and a burn-in oven;~~

~~providing a plastic film comprising a bump for electrically contacting the pad, and a conductive trace in electrical communication with the bump and the external lead;~~

~~placing the die on the test fixture;~~
~~bonding the bump to the pad; and~~

placing the external lead in electrical contact with the burn-in oven.

73. (currently amended) The method of claim 72 wherein the ~~test~~ fixture comprises a plurality of external leads and the ~~plastic~~ film comprises a plurality of bumps and a plurality of conductive traces in electrical communication with the bumps.

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Cont
74. (currently amended) The method of claim 72 the film comprises plastic.
~~further comprising removing the die from the test fixture with the bump bonded to the pad.~~

75. (currently amended) The method of claim 72 wherein the pad comprises a bondpad.
~~plastic film comprises a second bump bonded to the test fixture.~~
